



MITSUBISHI LSIs

M5M4257AP, J, L-85, -10, -12, -15

NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 262144-word by 1-bit dynamic RAMs, fabricated with the high performance N-channel silicon gate MOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential. The use of double-layer polysilicon process combined with silicide technology and a single-transistor dynamic storage cell provide high circuit density at reduced costs, and the use of dynamic circuitry including sense amplifiers assures low power dissipation. Multiplexed address inputs permit both a reduction in pins to the 18-pin plastic lead chip carrier configuration and an increase in system densities. In addition to the RAS only refresh mode, the Hidden refresh mode and CAS before RAS refresh mode are available.

FEATURES

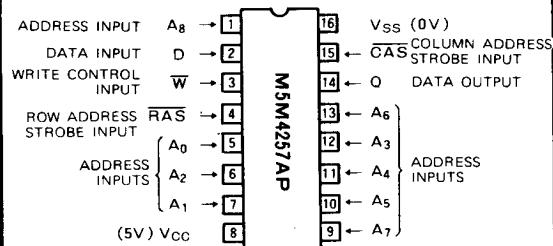
Type name	Access time (max) (ns)	Cycle time (min) (ns)	Power dissipation (typ) (mW)
M5M4257AP, J, L-85	85	160	300
M5M4257AP, J, L-10	100	190	260
M5M4257AP, J, L-12	120	220	230
M5M4257AP, J, L-15	150	260	200

- Standard 16 pin DIP, 18 pin PLCC, 16 pin ZIP
- Single 5V±10% supply
- Low standby power dissipation: 25mW (max)
- Low operating power dissipation:
 - M5M4257AP, J, L-85 385mW (max)
 - M5M4257AP, J, L-10 360mW (max)
 - M5M4257AP, J, L-12 330mW (max)
 - M5M4257AP, J, L-15 305mW (max)
- Unlatched output enables two-dimensional chip selection
- Early-write operation gives common I/O capability
- Read-modify-write, RAS-only-refresh, Nibble-mode capabilities
- CAS before RAS refresh mode capability
- All input terminals have low input capacitance and are directly TTL-compatible
- Output is three-state and directly TTL-compatible
- 256 refresh cycles every 4ms
- CAS controlled output allows hidden refresh

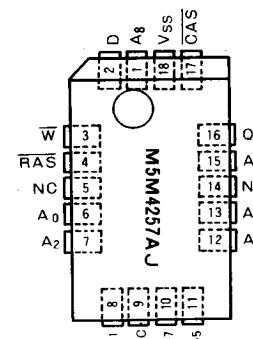
APPLICATION

Main memory unit for computers, Microcomputer memory

PIN CONFIGURATION (TOP VIEW)

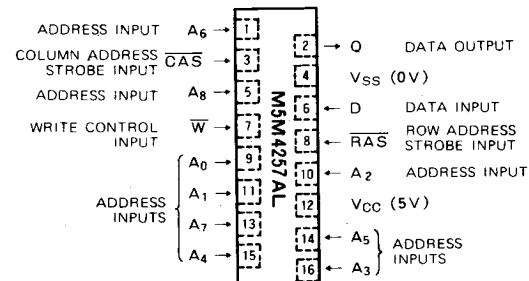


Outline 16P4H(DIP)



NC: NO CONNECTION

Outline 18P0A (PLCC)



Outline 16P5A (ZIP)

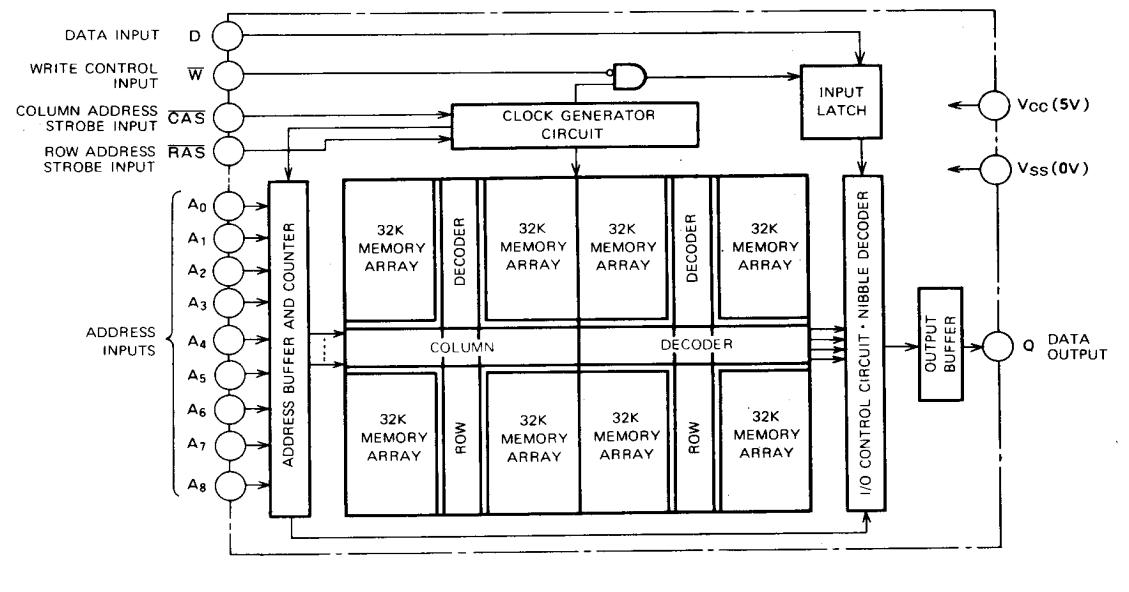
NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**FUNCTION**

The M5M4257AP, J, L provides, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g., page mode, RAS-only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs						Output Q	Refresh
	RAS	CAS	W	D	Row address	Column address		
Read	ACT	ACT	NAC	DNC	APD	APD	VLD	YES
Write	ACT	ACT	ACT	VLD	APD	APD	OPN	YES
Read-modify-write	ACT	ACT	ACT	VLD	APD	APD	VLD	YES
RAS-only refresh	ACT	NAC	DNC	DNC	APD	DNC	OPN	YES
Hidden refresh	ACT	ACT	DNC	DNC	DNC	DNC	VLD	YES
CAS before RAS refresh	ACT	ACT	DNC	DNC	DNC	DNC	OPN	YES
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO

Note: ACT: active, NAC: nonactive, DNC: don't care, VLD: valid, APD: applied, OPN: open.

BLOCK DIAGRAM

M5M4257AP, J, L-85, -10, -12, -15**NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM****ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1~7	V
V _I	Input voltage		-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a = 25°C	1000	mW
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-65~150	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.5	V
V _{IL}	Low-level input voltage, all inputs	-2		0.8	V

Note 1: All voltage values are with respect to V_{SS}.**ELECTRICAL CHARACTERISTICS** (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions			Limits			Unit
					Min	Typ	Max	
V _{OH}	High-level output voltage	I _{OH} = -5mA			2.4			V _{CC} V
V _{OL}	Low-level output voltage	I _{OL} = 4.2mA			0		0.4	V
I _{OZ}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 5.5V			-10		10	μA
I _I	Input current	0V ≤ V _{IN} ≤ V _{CC} · Other input pins = 0V			-10		10	μA
I _{CC1(AV)}	Average supply current from V _{CC} , operating (Note 3, 4)	M5M4257AP, J, L-85	RAS, CAS cycling t _{CR} = t _{CW} = min, output open			70		mA
		M5M4257AP, J, L-10				65		
		M5M4257AP, J, L-12				60		
		M5M4257AP, J, L-15				55		
I _{CC2}	Supply current from V _{CC} , standby	RAS = CAS = V _{IH}				4.5		mA
I _{CC3(AV)}	Average supply current from V _{CC} , refreshing (Note 3)	M5M4257AP, J, L-85	RAS cycling CAS = V _{IH} t _{C(RAS)} = min, output open			60		mA
		M5M4257AP, J, L-10				55		
		M5M4257AP, J, L-12				50		
		M5M4257AP, J, L-15				45		
I _{CC5(AV)}	Average supply current from V _{CC} , nibble mode (Note 3, 4)	M5M4257AP, J, L-85	RAS = V _{IL} , CAS cycling t _{CN} = min, output open			35		mA
		M5M4257AP, J, L-10				30		
		M5M4257AP, J, L-12				25		
		M5M4257AP, J, L-15				20		
I _{CC6(AV)}	Average supply current from V _{CC} , CAS before RAS refresh mode (Note 3)	M5M4257AP, J, L-85	CAS before RAS refresh cycling t _{C(RAS)} = min, Output open			65		mA
		M5M4257AP, J, L-10				60		
		M5M4257AP, J, L-12				55		
		M5M4257AP, J, L-15				50		
C _{I(A)}	Input capacitance, address inputs	V _I = V _{SS} f = 1MHz V _I = 25mVRms				5	pF	
C _{I(D)}	Input capacitance, data input					5	pF	
C _{I(W)}	Input capacitance, write control input					7	pF	
C _{I(RAS)}	Input capacitance, RAS input					10	pF	
C _{I(CAS)}	Input capacitance, CAS input					10	pF	
C _O	Output capacitance	V _O = V _{SS} , f = 1MHz, V _I = 25mVRms				7	pF	

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1(AV)}, I_{CC3(AV)}, I_{CC4(AV)} and I_{CC5(AV)} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.4: I_{CC1(AV)} and I_{CC4(AV)} are dependent on output loading. Specified values are obtained with the output open.

M5M4257AP, J, L-85, -10, -12, -15**NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM****TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh, and Page-Mode Cycle)**

(Ta = 0 ~ 70°C, VCC = 5V ± 10%, VSS = 0V, unless otherwise noted. See notes 5, 6 and 7.)

Symbol	Parameter	Alternative Symbol	Limits								Unit
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CRF}	Refresh cycle time	t _{REF}		4			4		4		4 ms
t _{w(RASH)}	RAS high pulse width	t _{RP}	65		80		90		100		ns
t _{w(RASL)}	RAS low pulse width	t _{RAS}	85	10000	100	10000	120	10000	150	10000	ns
t _{w(CASL)}	CAS low pulse width	t _{CAS}	45	10000	50	10000	60	10000	75	10000	ns
t _{w(CASH)}	CAS high pulse width (Note 8)	t _{CPN}	20		20		25		25		ns
t _{h(RAS-CAS)}	CAS hold time after RAS	t _{CSH}	85		100		120		150		ns
t _{h(CAS-RAS)}	RAS hold time after CAS	t _{RSH}	45		50		60		75		ns
t _{d(CAS-RAS)}	Delay time, CAS to RAS (Note 9)	t _{CRP}	10		10		10		10		ns
t _{d(RAS-CAS)}	Delay time, RAS to CAS (Note 10)	t _{RCD}	15	40	15	50	20	60	25	75	ns
t _{su(RA-RAS)}	Row address setup time before RAS	t _{ASR}	0		0		0		0		ns
t _{su(CA-CAS)}	Column address setup time before CAS	t _{ASC}	-5		-5		-5		-5		ns
t _{h(RAS-RA)}	Row address hold time after RAS	t _{RAH}	10		10		15		20		ns
t _{h(CAS-CA)}	Column address hold time after CAS	t _{CAH}	15		15		20		25		ns
t _{h(RAS-CA)}	Column address hold time after RAS	t _{AR}	55		65		80		100		ns
t _{THL}	Transition time	t _T	3	50	3	50	3	50	3	50	ns
t _{TLH}			3	50	3	50	3	50	3	50	ns

Note 5: An initial pause of 500μs is required after power-up followed by any eight RAS or RAS/CAS cycles before proper device operation is achieved.

6: The switching characteristics are defined as t_{THL} = t_{TLH} = 5ns.7: Reference levels of input signals are V_{IH} min and V_{IL} max. Reference levels for transition time are also between V_{IH} and V_{IL}.

8: Except for page-mode.

9: t_{d(CAS-RAS)} requirement is applicable for all RAS/CAS cycles.10: Operation within the t_{d(RAS-CAS)} max limit insures that t_{d(RAS)} max can be met. t_{d(RAS-CAS)} max is specified reference point only; ift_{d(RAS-CAS)} is greater than the specified t_{d(RAS-CAS)} max limit, then access time is controlled exclusively by t_{d(CAS)}.t_{d(RAS-CAS)} min = t_{h(RAS-RA)} min + 2t_{THL(t_{TLH})} + t_{su(CA-CAS)} min.**SWITCHING CHARACTERISTICS (Ta = 0 ~ 70°C, VCC = 5V ± 10%, VSS = 0V, unless otherwise noted)****Read Cycle**

Symbol	Parameter	Alternative Symbol	Limits								Unit
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CR}	Read cycle time	t _{RC}	160		190		220		260		ns
t _{su(R-CAS)}	Read setup time before CAS	t _{RCS}	0		0		0		0		ns
t _{h(CAS-R)}	Read hold time after CAS (Note 11)	t _{RCH}	0		0		0		0		ns
t _{h(RAS-R)}	Read hold time after RAS (Note 11)	t _{RRH}	10		10		10		10		ns
t _{dis(CAS)}	Output disable time (Note 12)	t _{OFF}	0	20	0	25	0	25	0	35	ns
t _{a(CAS)}	CAS access time (Note 13)	t _{CAC}		45		50		60		75	ns
t _{a(RAS)}	RAS access time (Note 14)	t _{RAC}		85		100		120		150	ns

Note 11: Either t_{h(RAS-R)} or t_{h(CAS-R)} must be satisfied for a read cycle.12: t_{dis(CAS)} max defines the time at which the output achieves the open circuit condition and is not reference to V_{OH} or V_{OL}.13: This is the value when t_{d(RAS-CAS)} ≥ t_{d(RAS-CAS)} max. Test conditions: Load = 2TTL, CL = 100pF.14: This is the value when t_{d(RAS-CAS)} < t_{d(RAS-CAS)} max. When t_{d(RAS-CAS)} ≥ t_{d(RAS-CAS)} max, t_{a(RAS)} will increase by the amount that t_{d(RAS-CAS)} exceeds the value shown. Test conditions: Load = 2TTL, CL = 100pF.**Write Cycle**

Symbol	Parameter	Alternative Symbol	Limits								Unit
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CW}	Write cycle time	t _{RC}	160		190		220		260		ns
t _{su(W-CAS)}	Write setup time before CAS (Note 17)	t _{WCS}	-10		-10		-10		-10		ns
t _{h(CAS-W)}	Write hold time after CAS	t _{WCH}	15		20		25		30		ns
t _{h(RAS-W)}	Write hold time after RAS	t _{WCR}	55		70		85		105		ns
t _{h(W-RAS)}	RAS hold time after write	t _{RWL}	30		35		40		45		ns
t _{h(W-CAS)}	CAS hold time after write	t _{CWL}	30		35		40		45		ns
t _{WP}	Write pulse width	t _{WP}	15		20		25		30		ns
t _{su(D-CAS)}	Data-in setup time before CAS	t _{DS}	0		0		0		0		ns
t _{h(CAS-D)}	Data-in hold time after CAS	t _{DH}	15		20		25		30		ns
t _{h(RAS-D)}	Data-in hold time after RAS	t _{DHR}	55		70		85		105		ns



M5M4257AP, J, L-85, -10, -12, -15**NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM****Read-Write and Read-Modify-Write Cycles**

Symbol	Parameter	Alternative Symbol	Limits								Unit	
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
t_{CRW}	Read-write cycle time (Note 15)	t_{RWC}	185		220		255		295		ns	
t_{CRMW}	Read-modify-write cycle time (Note 16)	t_{RMWC}	195		235		265		310		ns	
$t_h(W\cdot RAS)$	RAS hold time after write	t_{RWL}	30		35		40		45		ns	
$t_h(W\cdot CAS)$	CAS hold time after write	t_{CWL}	30		35		40		45		ns	
$t_w(w)$	Write pulse width	t_{WP}	15		20		25		30		ns	
$t_{su}(R\cdot CAS)$	Read setup time before CAS	t_{RCS}	0		0		0		0		ns	
$t_d(RAS\cdot W)$	Delay time, RAS to write (Note 17)	t_{RWD}	70		90		110		135		ns	
$t_d(CAS\cdot W)$	Delay time, CAS to write (Note 17)	t_{CWD}	30		40		50		60		ns	
$t_{su}(D\cdot W)$	Data-in setup time before write	t_{DS}	0		0		0		0		ns	
$t_h(w\cdot D)$	Data-in hold time after write	t_{DH}	15		20		25		30		ns	
$t_{dis}(CAS)$	Output disable time	t_{OFF}	0	20	0	25	0	30	0	35	ns	
$t_a(CAS)$	CAS access time (Note 13)	t_{CAC}		45		50		60		75	ns	
$t_a(RAS)$	RAS access time (Note 14)	t_{RAC}		85		100		120		150	ns	

Note 15: t_{CRW} min is defined as t_{CRW} min = $t_d(RAS\cdot W)$ max + $t_d(CAS\cdot W)$ min + $t_h(W\cdot RAS)$ + $t_w(RASH)$ + 3 $t_{TLH}(t_{TLH})$.16: t_{CRMW} min is defined as t_{CRMW} min = $t_d(RAS\cdot W)$ max + $t_h(W\cdot RAS)$ + $t_w(RASH)$ + 3 $t_{TLH}(t_{TLH})$.17: $t_{su}(W\cdot CAS)$, $t_d(RAS\cdot W)$, and $t_d(CAS\cdot W)$ do not define the limits of operation, but are included as electrical characteristics only.When $t_{su}(W\cdot CAS) \geq t_{su}(W\cdot CAS)$ min, an early-write cycle is performed, and the data output keeps the high-impedance state.When $t_d(RAS\cdot W) \geq t_d(RAS\cdot W)$ min and $t_d(CAS\cdot W) \geq t_{su}(W\cdot CAS)$ min a read-write cycle is performed, and the data of the selected address will be read out on the data output.For all conditions other than those described above (delayed write), the condition of data output (at access time and until CAS goes back to V_{IH}) is not defined.**Nibble Mode Cycle**

Symbol	Parameter	Alternative Symbol	Limits								Unit	
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
t_{CN}	Nibble mode cycle time	t_{NC}	45		50		55		70		ns	
$t_{aN}(CAS)$	Nibble mode access time	t_{NAC}		20		25		30		40	ns	
$t_{WN}(CASL)$	Nibble mode CAS low pulse width	t_{NCAS}	20		25		30		40		ns	
$t_{WN}(CASH)$	Nibble mode precharge time	t_{NP}	15		15		15		20		ns	
$t_{hn}(CAS\cdot RAS)$	Nibble mode RAS naid time	t_{NRSH}	20		25		30		40		ns	
$t_{dn}(CAS\cdot W)$	Nibble mode CAS to WRITE delay	t_{NCWD}	20		25		30		40		ns	
$t_{WNRMW}(CASL)$	Nibble mode RMW CAS pulse width	t_{NCRW}	45		55		65		85		ns	
$t_{WNRMW}(W\cdot CAS)$	Nibble mode WRITE to CAS lead time	t_{NCWL}	20		25		30		40		ns	
$t_{WNRMW}(CAS\cdot RAS)$	Nibble mode RMW RAS hold time	t_{NWSH}	45		55		65		85		ns	
$t_{sun}(W\cdot CAS)$	Nibble mode WRITE setup time before CAS	t_{NWCS}	0		0		0		0		ns	

CAS before RAS Refresh Cycle (Note 18)

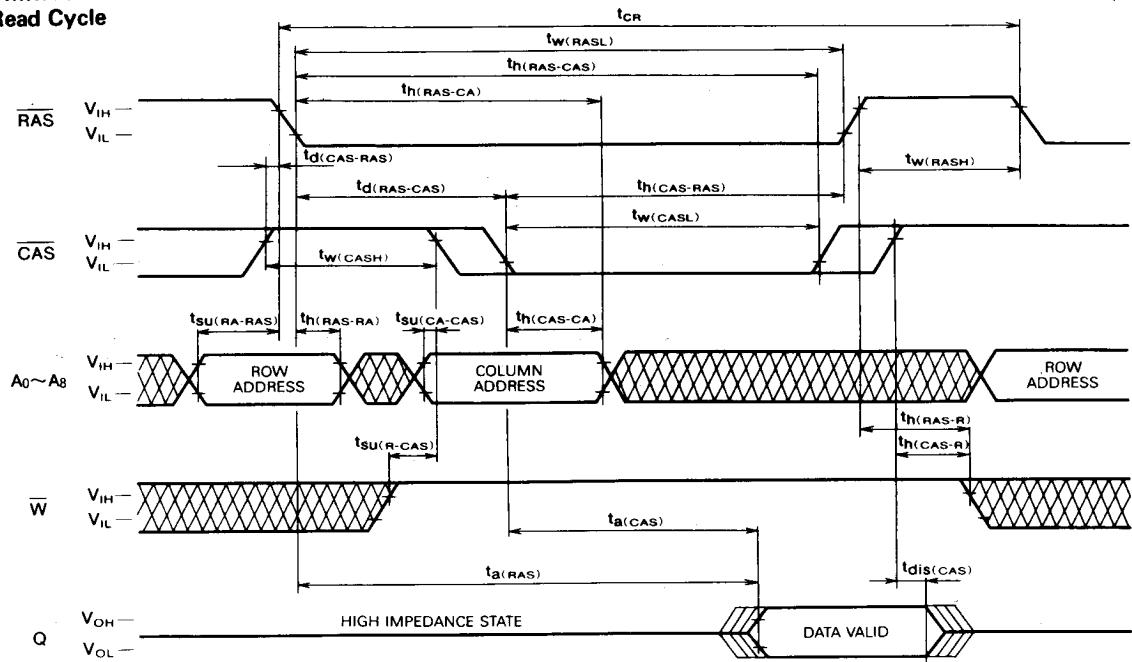
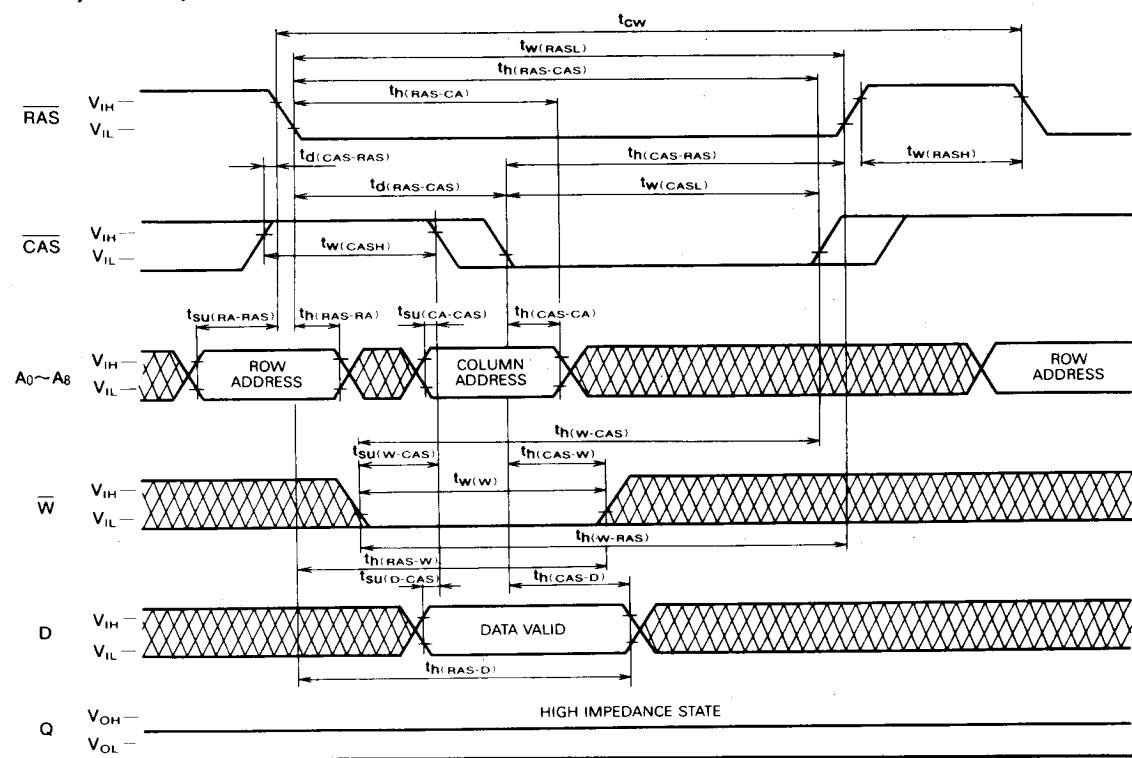
Symbol	Parameter	Alternative Symbol	Limits								Unit	
			M5M4257A-85		M5M4257A-10		M5M4257A-12		M5M4257A-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
$t_{sur}(CAS\cdot RAS)$	CAS setup time for auto refresh	t_{CSR}	10		10		10		10		ns	
$t_{hr}(RAS\cdot CAS)$	CAS hold time for auto refresh	t_{CHR}	15		20		25		30		ns	
$t_{dr}(RAS\cdot CAS)$	Precharge to CAS active time	t_{RPC}	0		0		0		0		ns	

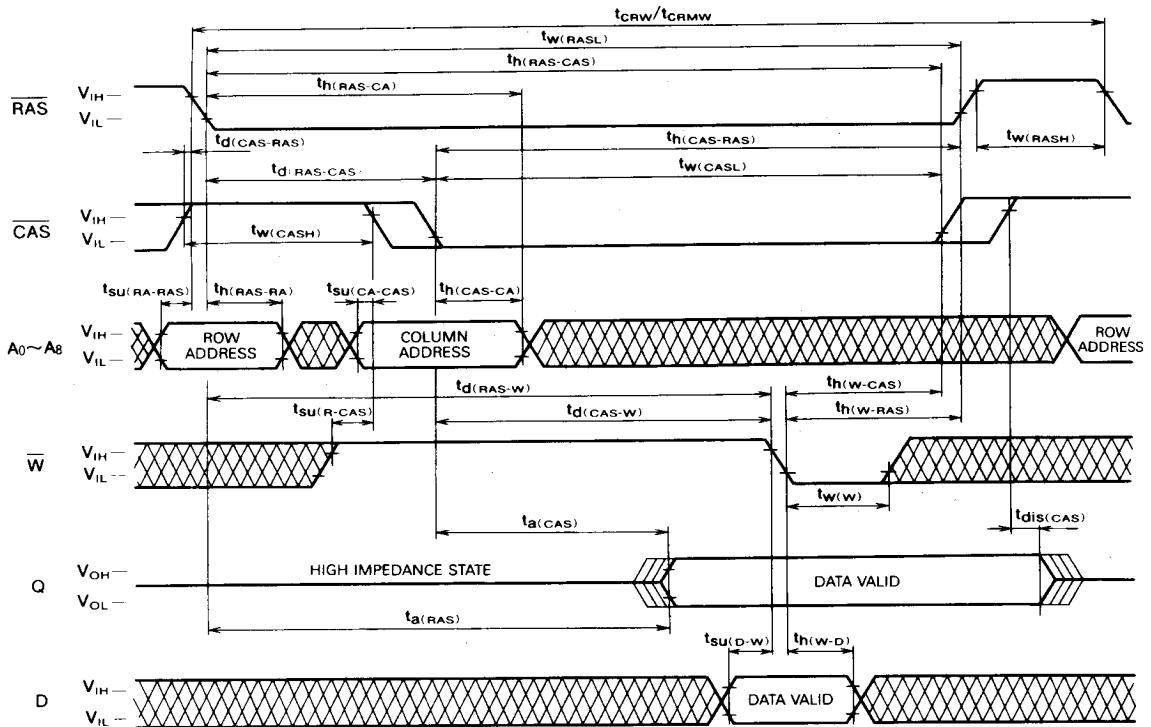
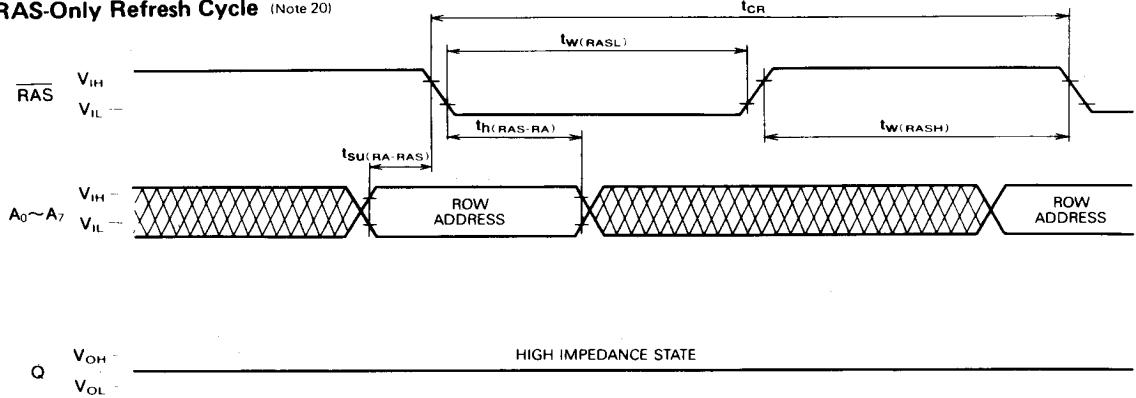
Note 18: Eight or more CAS before RAS cycles is necessary for proper operation of CAS before RAS refresh mode.

Nibble Mode Addressing Sequence Example

Sequence	Nibble bit	Column address								Row address								External address	
		A ₀	A ₁	A ₂	A ₃	A ₄	A ₅	A ₆	A ₇	A ₀	A ₁	A ₂	A ₃	A ₄	A ₅	A ₆	A ₇	A ₈	
RAS/CAS	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	0
toggle CAS	2	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1	1	1
toggle CAS	3	0	1	0	1	0	1	0	1	1	0	1	0	1	0	1	0	1	0
toggle CAS	4	0	1	0	1	0	1	0	1	1	0	1	0	1	0	1	0	1	1
toggle CAS	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	0

Internally generated address

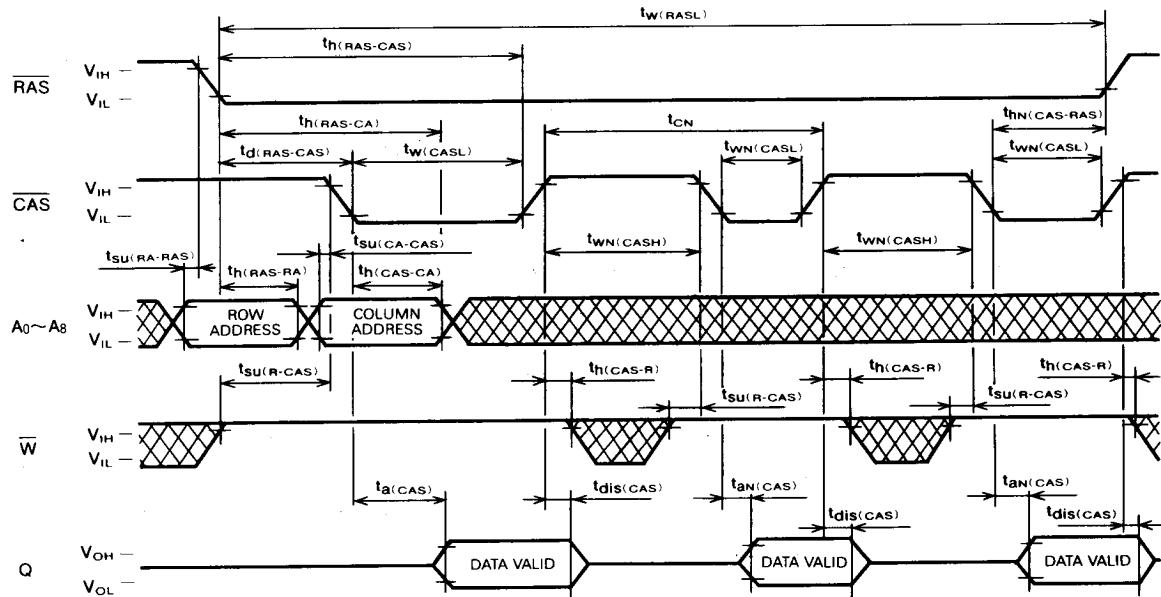
NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**TIMING DIAGRAMS** (Note 19)**Read Cycle****Write Cycle (Early Write)**

NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**Read-Write and Read-Modify-Write Cycles****RAS-Only Refresh Cycle (Note 20)**

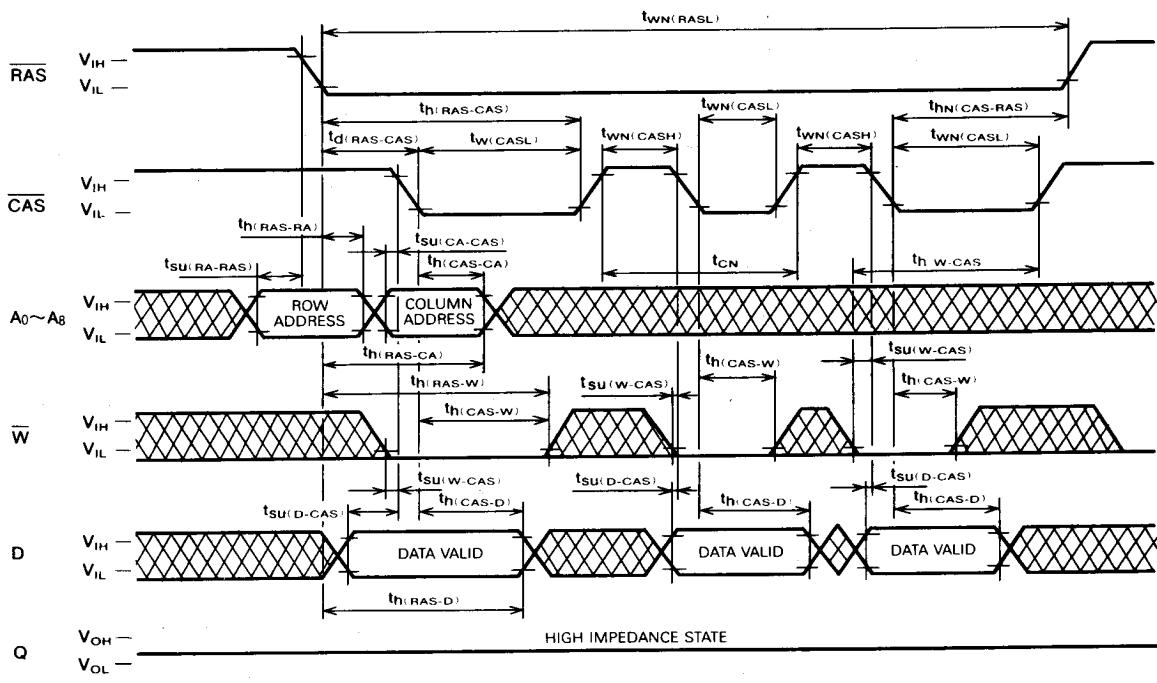
Note 19. Indicates the don't care input.

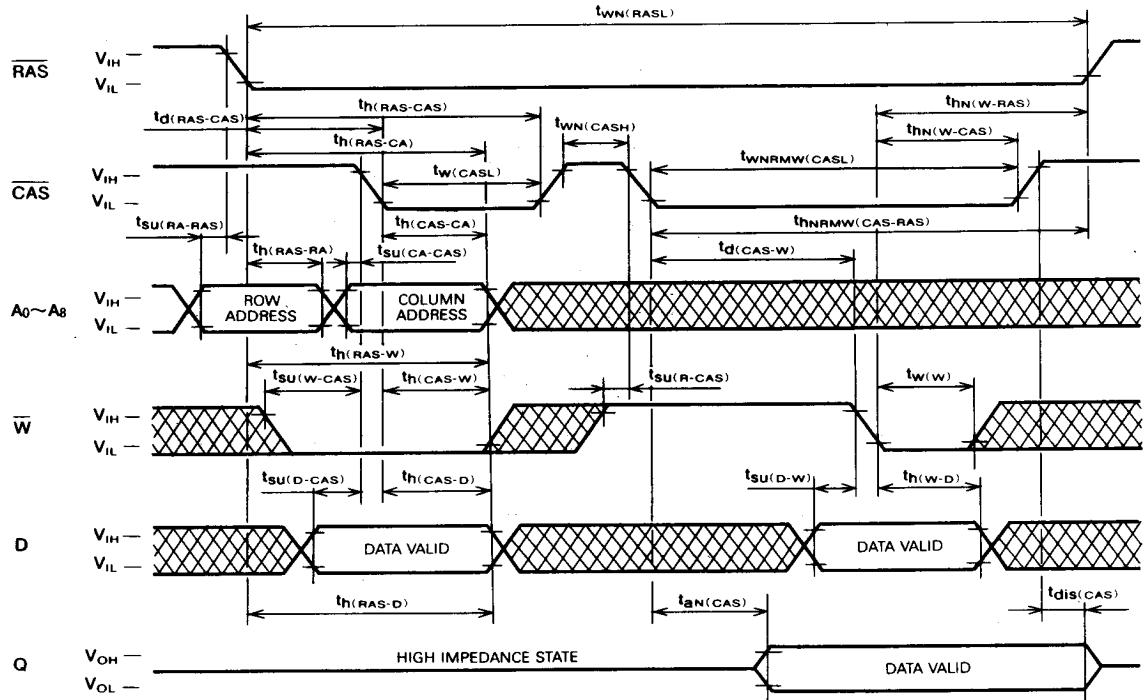
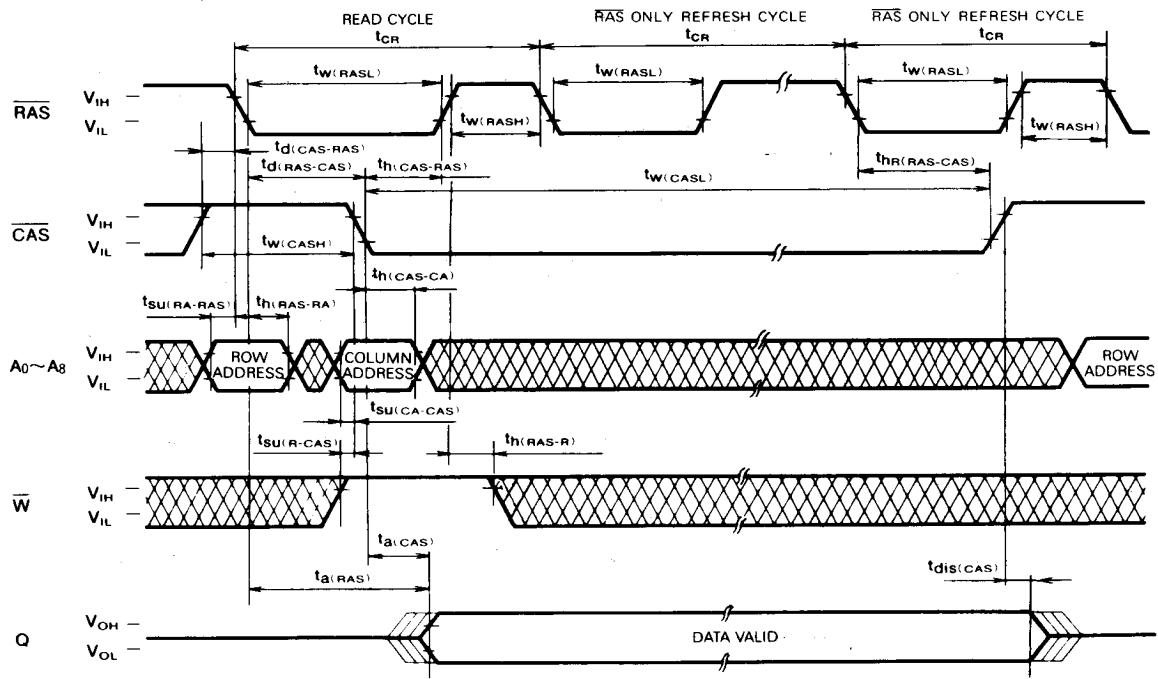
Note 20. $\overline{C\!A\!S} = V_{IH}$, $\overline{W} = \text{don't care}$.
A8 may be V_{IH} or V_{IL} .

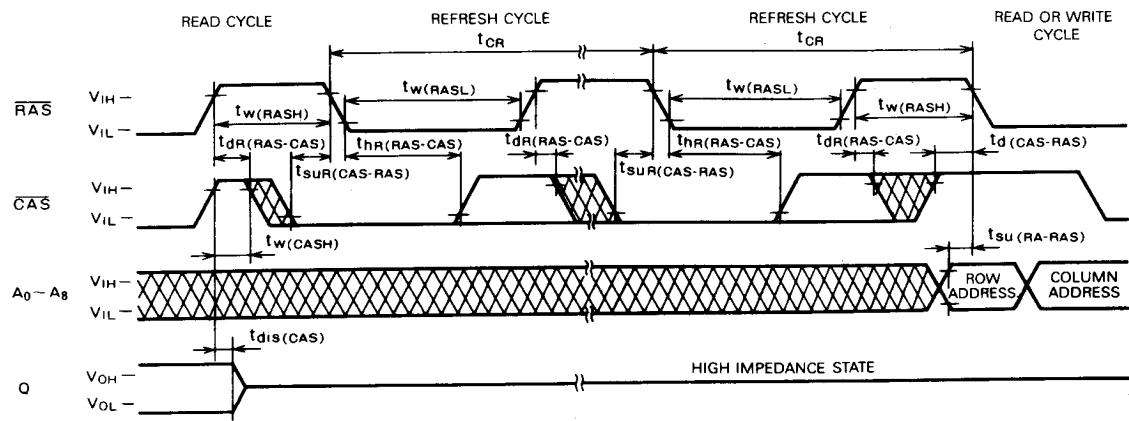
The center-line indicates the high-impedance state.

NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**Nibble Mode Read Cycle (Note 21)**

Note 21: Pin 1 at Row Time and Column Time Determines the Starting Address of the Nibble Cycle.

Nibble Mode Write Cycle (Early Write)

NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**Nibble Mode Read-Modify-Write Cycle****Hidden Refresh Cycle**

NIBBLE MODE 262144-BIT (262144-WORD BY 1-BIT) DYNAMIC RAM**CAS before RAS Refresh Cycle (Note 22)**

Note 22. W, D = don't care.